

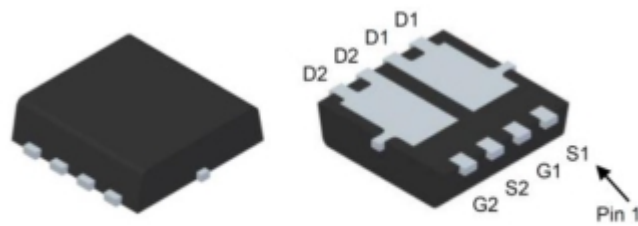
## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
30V	10mΩ@10V	12A
	15mΩ@4.5V	

## Feature

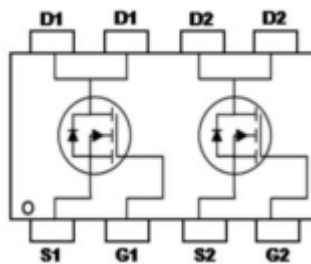
- Enhancement mode
- Low on-resistance  $R_{DS(on)}$
- Pb-free lead plating; RoHS compliant

## Package

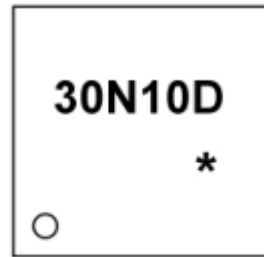


PDFNWB3.3×3.3-8L-B

## Circuit diagram



## Marking



30N10D    =Device Code  
\*            =Month Code

## Absolute maximum ratings

(T<sub>a</sub>=25°C unless otherwise noted)

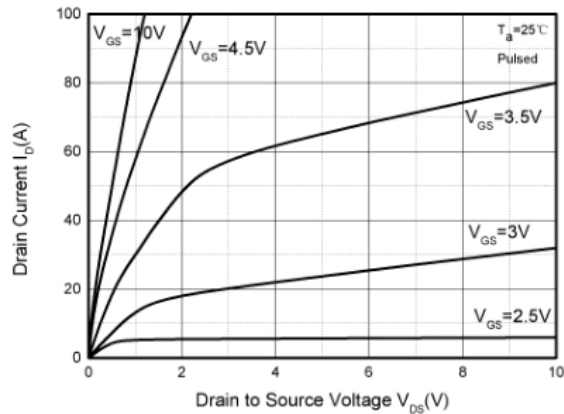
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	12	A
Pulsed Drain Current	I <sub>DM</sub>	48	A
Total Power Dissipation	P <sub>D</sub> @T <sub>C</sub> =25°C	22	W
Thermal Resistance from Junction to Case	R <sub>θJC</sub>	5.6	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 To 150	°C

## Electrical characteristics

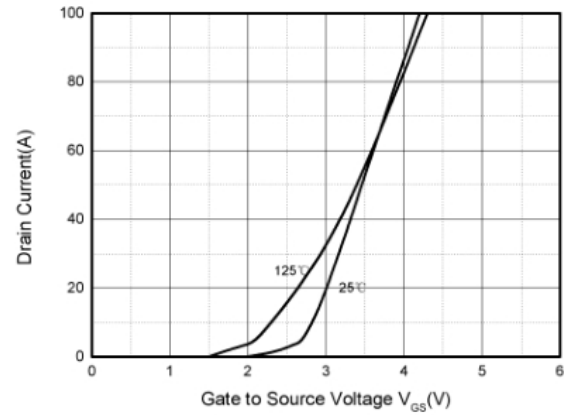
(T<sub>A</sub>=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$BV_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	2.2	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS} = 24V, V_{GS} = 0V, T_J = 25^{\circ}C$			1	$\mu A$
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	$\mu A$
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 12A$		10	14	m $\Omega$
		$V_{GS} = 4.5V, I_D = 10A$		15	21	
Dynamic Characteristics						
Input Capacitance	$C_{iss}$	$V_{DS} = 15V, V_{GS} = 0V, f = 1MHz$		720		pF
Output Capacitance	$C_{oss}$			100		
Reverse Transfer Capacitance	$C_{rss}$			85		
Total Gate Charge	$Q_g$	$V_{DS} = 15V, V_{GS} = 10V, I_D = 10A$		15		pF
Gate-Source Charge	$Q_{gs}$			5		
Gate-Drain Charge	$Q_{gd}$			3.5		
Switching Characteristics						
Turn-on Delay Time	$T_{d(on)}$	$V_{DD} = 15V, V_{GS} = 10V, R_G = 3\Omega, I_D = 20A$		5		nS
Turn-on Rise Time	$T_r$			4		
Turn-off Delay Time	$T_{d(off)}$			20		
Turn-off Fall Time	$T_f$			5.5		
Source-Drain Diode Characteristics						
Diode Forward Voltage	$V_{SD}$	$I_S = 1A, V_{GS} = 0V, T_J = 25^{\circ}C$			1.2	V

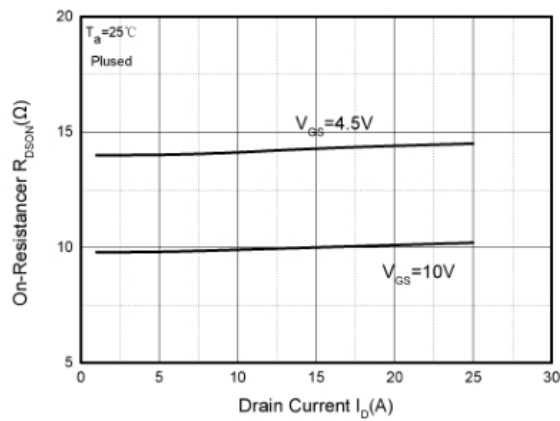
## Typical Characteristics



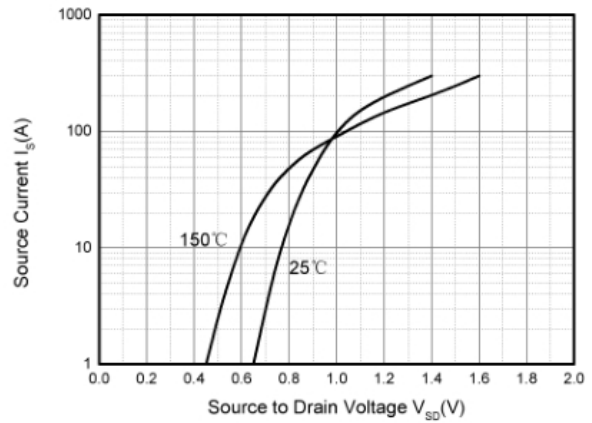
Output Characteristics



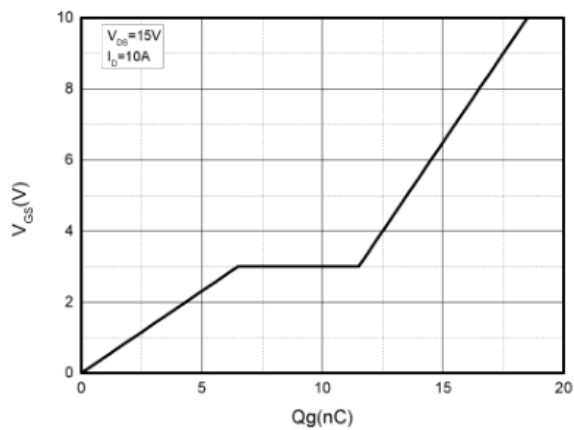
Transfer Characteristics



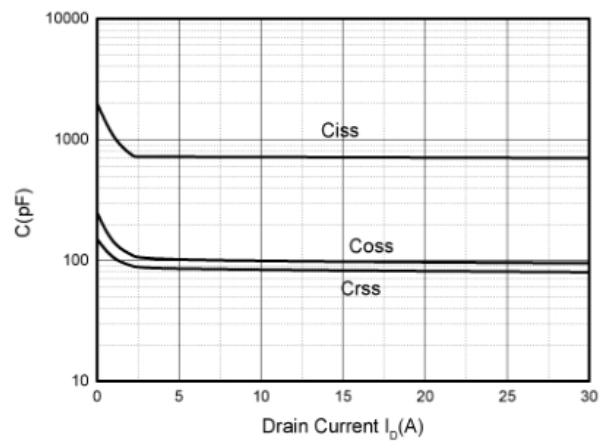
On-Resistance vs. Drain current



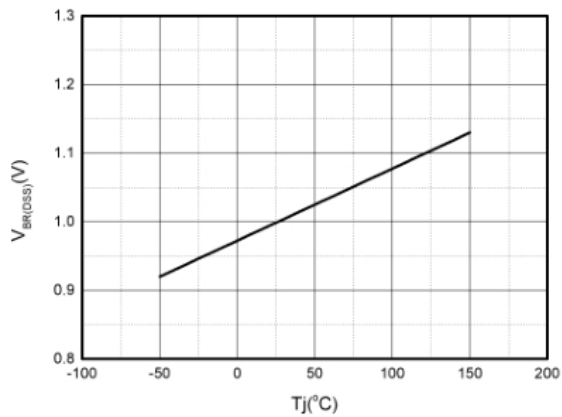
Source Current vs. Source to Drain Voltage



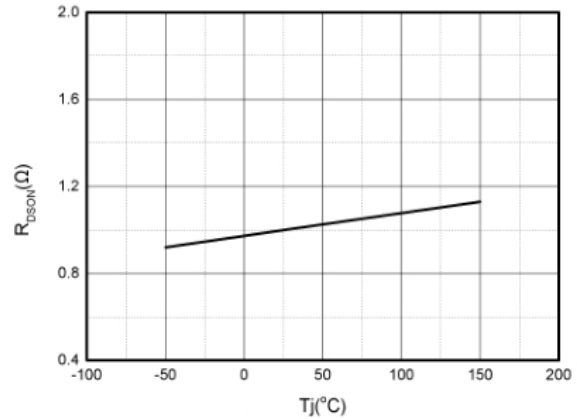
Gate Charge Characteristics



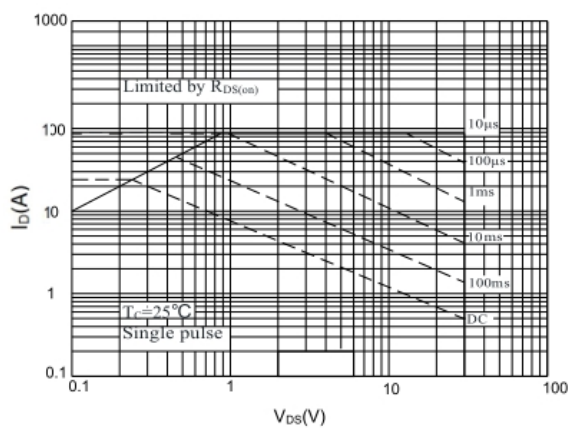
Capacitance Characteristics



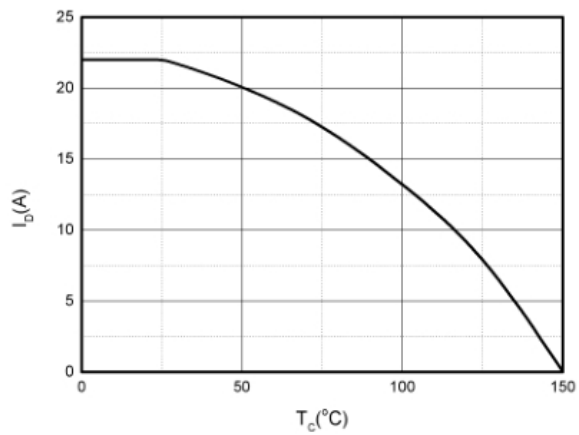
Normalized Breakdown Voltage vs. Junction Temperature



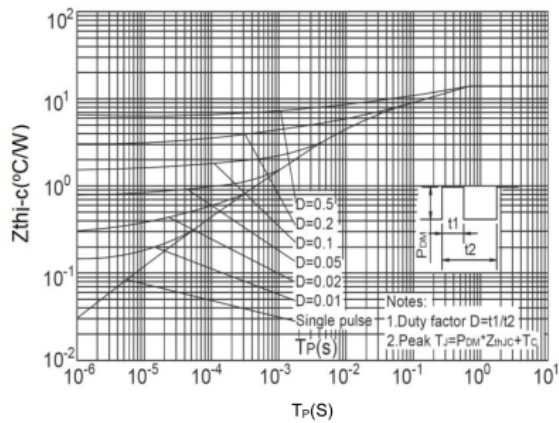
Normalized on Resistance vs. Junction Temperature



Maximum Safe Operating Area

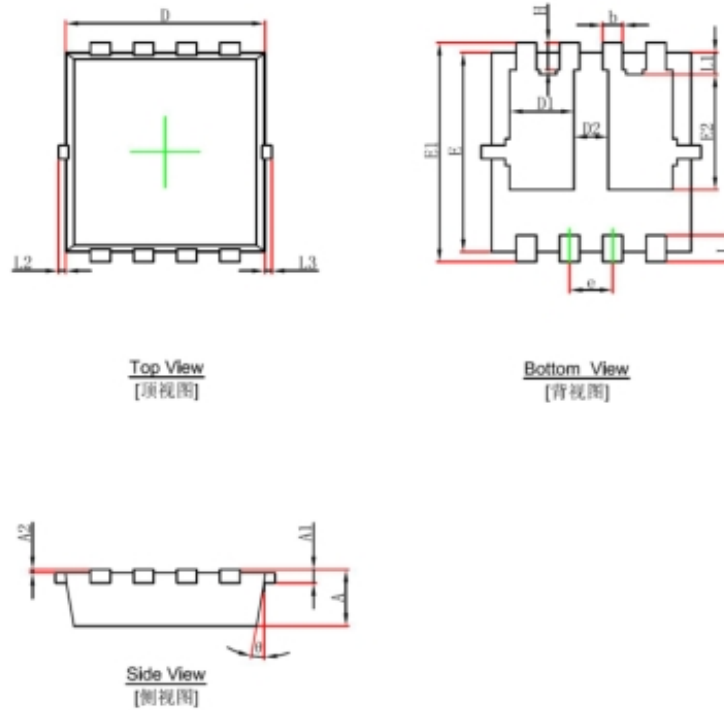


Maximum Continuous Drain Current vs. Case Temperature



Maximum Effective Transient Thermal Impedance, Junction-to-Case

## PDFNWB3.3×3.3-8L-B Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	0.935	1.135	0.037	0.045
D2	0.280	0.480	0.011	0.019
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
$\theta$	9°	13°	9°	13°